



TSMC Board of Directors Meeting Resolutions

Hsinchu, Taiwan, R.O.C., Aug. 11, 2020 – TSMC (TWSE: 2330, NYSE: TSM) today held a meeting of the Board of Directors, which passed the following resolutions:

1. Approved the distribution of a NT\$2.5 per share cash dividend for the second quarter of 2020, and set December 23, 2020 as the record date for common stock shareholders entitled to participate in this cash dividend distribution, and the ex-dividend date for the common shares shall be December 17, 2020. As required by Article 165 of Taiwan's Company Law, the shareholders' register shall be closed for five days prior to the record date (December 19 through December 23, 2020) for registration transfer, and the dividend will be paid on January 14, 2021. In addition, the ex-dividend date for TSMC American Depositary Shares (ADSs) will be December 17, 2020. The record date for TSMC ADSs entitled to participate in this cash dividend distribution will be December 18, 2020.
2. Approved capital appropriations of approximately US\$5,271.6 million (approximately NT\$152.9 billion) for purposes including: 1) Installation and expansion of advanced technology capacity; 2) Installation of specialty technology capacity; 3) Installation of advanced packaging capacity; 4) Fab construction, installation of fab facility systems, and capitalized leased assets; 5) Fourth quarter 2020 R&D capital investments and sustaining capital expenditures.
3. Approved the issuance of US dollar-denominated unsecured corporate bonds for an amount not to exceed US\$1 billion, and approved the provision of a guarantee to TSMC Global, a wholly-owned foreign subsidiary of TSMC, for its issuance of US dollar-denominated senior unsecured corporate bonds for an amount not to exceed US\$3 billion, to finance TSMC's capacity expansion.
4. Approved the promotion of Business Development Vice President Dr. Kevin Zhang to Senior Vice President.



About TSMC

TSMC pioneered the pure-play foundry business model when it was founded in 1987, and has been the world's largest dedicated semiconductor foundry ever since. The Company supports a thriving ecosystem of global customers and partners with the industry's leading process technologies and portfolio of design enablement solutions to unleash innovation for the global semiconductor industry. With global operations spanning Asia, Europe, and North America, TSMC serves as a committed corporate citizen around the world.

TSMC deployed 272 distinct process technologies, and manufactured 10,761 products for 499 customers in 2019 by providing broadest range of advanced, specialty and advanced packaging technology services. TSMC is the first foundry to provide 5-nanometer production capabilities, the most advanced semiconductor process technology available in the world. The Company is headquartered in Hsinchu, Taiwan. For more information please visit <https://www.tsmc.com>.

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